

PCN Number:	20190423003.1		PCN Date:	April 23 2019	
Title:	Add Au as Alternative Wire Base Metal for the THS4551IRUNR/T				
Customer Contact:	PCN Manager	Dept:	Quality Services		
Proposed 1st Ship Date:	July 23 2019	Estimated Sample Availability:	Date provided at sample request		
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
				<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the qualification of Au as an additional bond wire option for the THS4551IRUNR/T. This device will remain in current assembly facilities and there will be no other piece part changes:					
	Current Wire		Additional Wire		
	Cu, 1.0 mils		Cu, 1.0 mils or Au, 0.96 mils		
Reason for Change:					
Continuity of Supply					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Anticipated impact on Material Declaration					
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .		
Changes to product identification resulting from this PCN:					
None					
Product Affected:					
	THS4551IRUNR		THS4551IRUNT		

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: THS4551IRUNR	QBS Product Reference: THS4551IDGK	QBS Process Reference: THS4521ID	QBS Package Reference: OPA2837IRUN	QBS Package Reference: THS4551IRUN (Cu wire)
AC	Autoclave, 121C	96 Hours	-	-	3/231/0	-	-
CDM	ESD - CDM	1000 V	-	-	3/9/0	1/3/0	-
CDM	ESD - CDM	1500 V	-	1/3/0	-	-	-
ED	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/30/0	3/90/0	1/30/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-	3/231/0
HBM	ESD - HBM	1300 V	-	-	3/9/0	-	-
HBM	ESD - HBM	2500 V	-	1/3/0	-	1/3/0	1/3/0
HTOL	Life Test, 150C	300 Hours	-	-	3/348/0	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	3/231/0	3/231/0
LU	Latch-up	Per JESD78	-	1/6/0	3/18/0	1/6/0	-
SD	Pb Free Solderability	Pb Free/Solderability	-	-	-	-	3/66/0
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	-	3/231/0	3/231/0	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	1/77/0	-	-	3/228/0	3/231/0
WBP	Bond Pull	76 Wires, 3 units min	1/76/0	-	-	-	-
WBS	Ball Bond Shear	76 balls, 3 units min	1/76/0	-	-	-	-
XRAY	X-RAY	Top	-	-	3/15/0	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7 eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7 eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:
Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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